

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Confirmation No. 4508

Toshifumi KIMBA et al.

Docket No. 2000-1706A

Serial No. 09/734,737

Group Art Unit 2877

Filed December 13, 2000

Examiner Hoa Q. Pham

SUBSTRATE FILM THICKNESS
MEASUREMENT METHOD,
SUBSTRATE FILM THICKNESS
MEASUREMENT APPARATUS
AND SUBSTRATE PROCESSING
APPARATUS

AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Responsive to the Office Action of February 26, 2003, please amend the above-identified application as follows.

In the Specification and Abstract:

Kindly replace the original specification and abstract with the enclosed substitute specification and abstract.

In the Claims:

Kindly cancel claims 1-19 presently pending in the application without prejudice.

LECHMOND SELECT SECOND